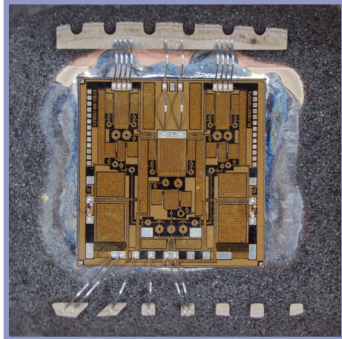


# DECAPSULATION SERVICE

- LASER ABLATION DECAPSULATION
- WET CHEMICAL DECAPSULATION
- MICROWAVE INDUCED PLASMA (MIP) DECAPSULATION
- MECHANICAL DECAPSULATION
- LED LENS REMOVAL
- HIGH PIN COUNT PACKAGE DECAPSULATION

## DECAPSULATION SERVICE

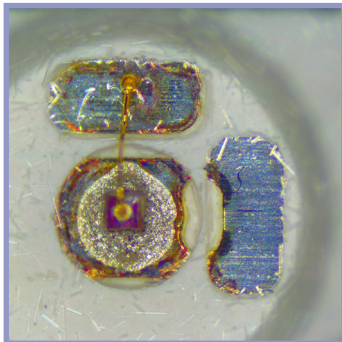
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### LASER DECAPSULATION

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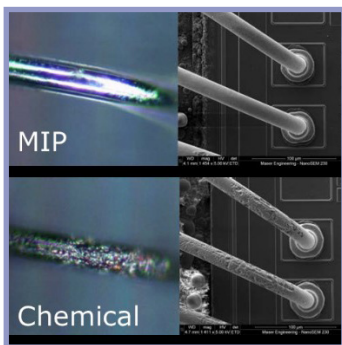
- Laser assisted decapsulation to minimize the amount of chemicals needed
- Exposure of bond wires / wedge bonds without the use of any chemicals
- Laser marking ability for different materials
- Ability to cut glass and remove glass covers of sensors
- Selective area decapsulation



### WET CHEMICAL DECAPSULATION

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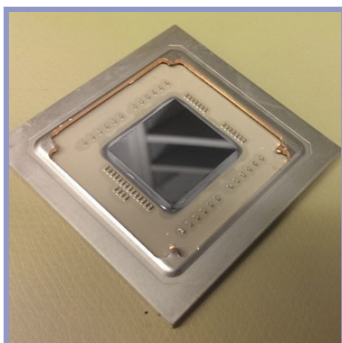
- Plastic package decapsulation of Cu, Au and Al wired packages
- Polyimide layer removal of semiconductor products
- Decapsulation of devices soldered to a PCB
- RDL removal from WLCSP devices
- Complete package removal keeping the die and bond wires intact
- GaAs die decapsulation



### MICROWAVE INDUCED PLASMA (MIP) DECAPSULATION

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- Plasma decapsulation of copper and silver bond wire packages
- No passivation layer / die damage due to the decapsulation process
- Cu protecting palladium coating unharmed
- Effective decapsulation method for harsh environment tested samples
- EOS damage unharmed after decapsulation
- Completely chemical free decapsulation process
- Silicone LED lens removal



### MECHANICAL DECAPSULATION

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- Automated Selected Area Polishing tool (ASAP)
- De-lidding of ceramic samples
- Back side QFN sample preparation keeping the down bonds intact
- Mechanical opening of round TO-xx devices
- Through PCB sample preparation for back-side failure localization
- Stacked die removal